MATERIAL DECLARATION SHEET

Package Type	TCS-DL004-750-WH		
Product Line	Semiconductor Products		
Compliance Date	1 June 2012		
RoHS Compliant	Yes	MSL	1

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy resin	0.023141	Fused Silica	60676-86-0	87.70	41.08	46.85
				Epoxy resin	Trade secret	5.00	2.34	
				Epoxy CN	29690-82-2	2.00	0.94	
				Phenol resin	Trade secret	5.00	2.34	
				Carbon Black	1333-86-4	0.30	0.14	
2	Leadframe	Copper alloy	0.020099	Copper	7440-50-8	93.32	38.12	40.68
				Iron	7439-89-6	2.20	0.90	
				Zinc	7440-66-6	0.01	0.00	
				Phosphorous	7723-14-0	0.03	0.01	
				Silver (Plating)	7440-22-4	4.45	1.65	
3	Chip	Silicon	0.005061	Silicon	7440-21-3	99.43	10.23	10.25
				Aluminum	7429-90-5	0.57	0.02	
4	Die Attach	Silver epoxy	0.000197	Silver	7440-22-4	75.00	0.30	0.40
				Epoxy	9003-36-5	25.00	0.10	
5	Bond wires	Gold	0.000051	Gold	7440-57-5	100.00	0.10	0.10
6	Terminal Finish	Matte Tin	0.000852	Matte Tin	7440-31-5	100.00	1.72	1.72
		Total Weight	0.0494000					

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.

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